

2SC4626J

Silicon NPN epitaxial planar type

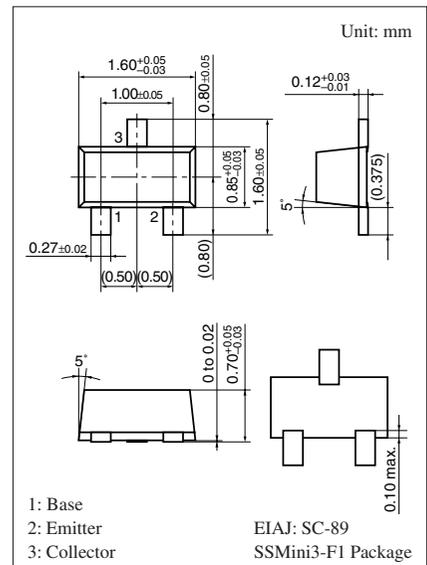
For high-frequency amplification

■ Features

- Optimum for RF amplification of FM/AM radios
- High transition frequency f_T
- SS-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector to base voltage	V_{CBO}	30	V
Collector to emitter voltage	V_{CEO}	20	V
Emitter to base voltage	V_{EBO}	5	V
Collector current	I_C	30	mA
Collector power dissipation	P_C	125	mW
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$



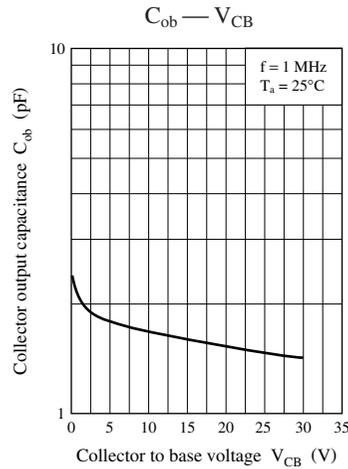
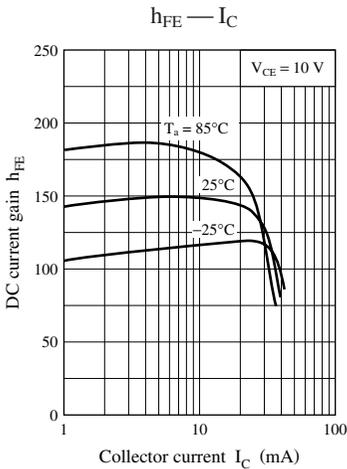
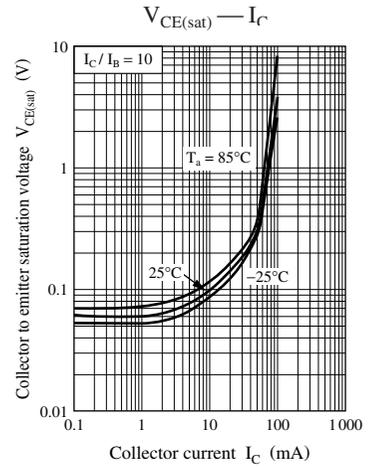
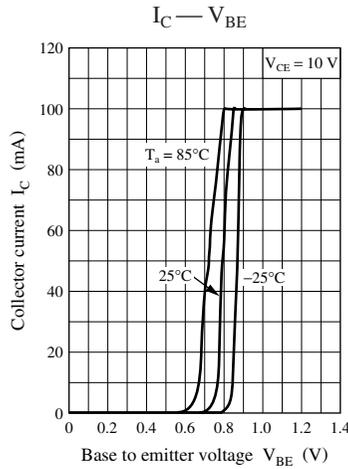
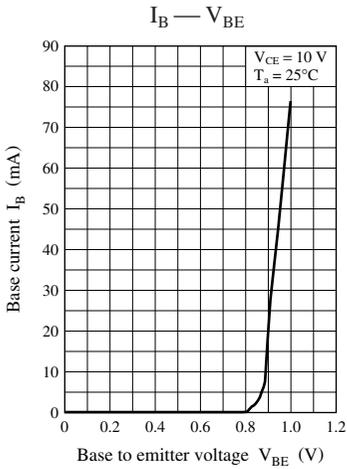
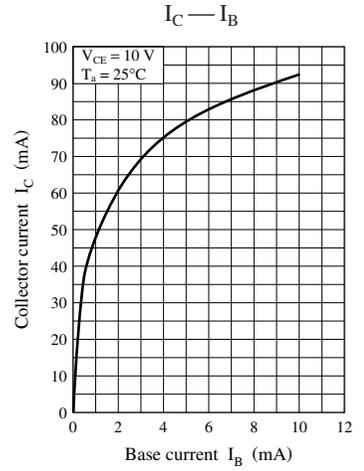
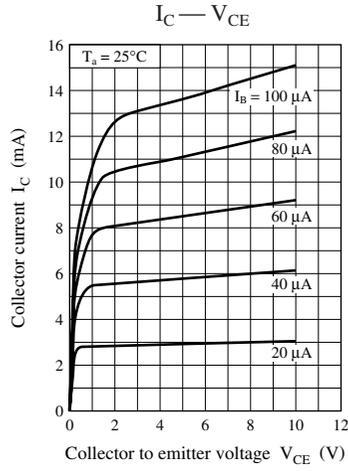
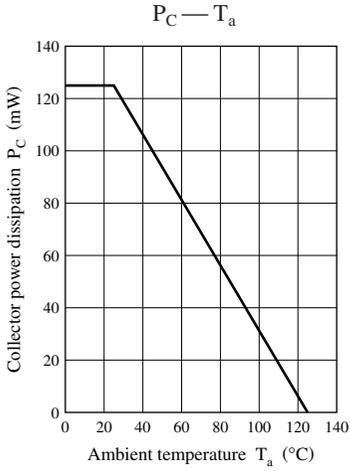
Marking Symbol: V

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector cutoff current	I_{CBO}	$V_{CB} = 10\text{ V}, I_E = 0$			0.1	μA
DC current gain *	h_{FE}	$V_{CB} = 10\text{ V}, I_E = -1\text{ mA}$	70		220	
Gain bandwidth product	f_T	$V_{CB} = 10\text{ V}, I_E = -1\text{ mA}, f = 200\text{ MHz}$	150	250		MHz
Reverse transfer impedance	Z_{rb}	$V_{CB} = 10\text{ V}, I_E = -1\text{ mA}, f = 2\text{ MHz}$		22	50	Ω
Common emitter reverse transfer capacitance	C_{re}	$V_{CB} = 10\text{ V}, I_E = -1\text{ mA}, f = 10.7\text{ MHz}$		0.9	1.5	pF
Noise figure	NF	$V_{CB} = 10\text{ V}, I_E = -1\text{ mA}, f = 5\text{ MHz}$		2.8	4.0	dB

Note) *: h_{FE} rank classification

Rank	B	C	No rank
h_{FE}	70 to 140	110 to 220	70 to 220



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